

## An Introduction To LemTech Group

■ ■ ■ *Leading **E**ngineering & **M**anufacturing **T**echnology*



# Content

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## ■ Core Business Activities

- Tooling & Design Capabilities
- Stamping Solutions in Mobile
- Automotive Business
- Thermal Solution in 3C Products
- New Technology developing for Server
- Slide Rails developing for Server

## ■ Our Valued Customers

## ■ Financial Report

## Corporate Profile

- Global Provider of Choice for :  
***Precision Tooling, Metal Stamping, Electro- Mechanical & Custom Sub Assy Solutions; with expertise in Thermal Solutions, Metal Hinges & Slide Rails for the Computing, Consumer, Automotive & Infrastructure Industry***
- Manufacturing sites/offices in 4 countries
- Listed on the Taiwan Stock Exchange in 2011
- Group revenue of USD75 million for FY13
- ISO9001:2000, ISO/TS16949, ISO14001:2004 certified





- **TAIWAN**
- ★ Taipei (HQ)

- **CHINA**
- Kunshan
- Hong Kong

- **THAILAND**
- Ayutthaya

- **USA**
- San Jose, CA

- **5 Manufacturing Sites/Offices**
- ~ Total Floor Space: 500,000 sqft
  
- ~ Total Headcount 1,200

# Core Business Activities

# Tooling & Design Capabilities



## Product Design Platforms

3D : Solidworks/pro-E

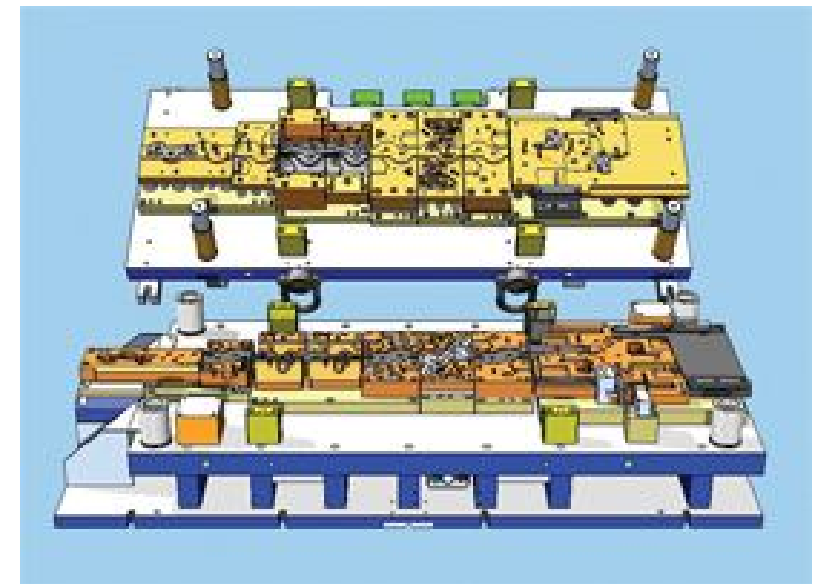
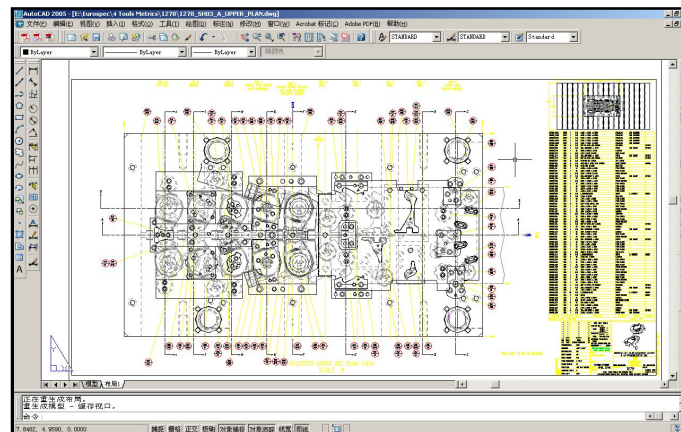
2D : AutoCad



## Tool Design Platforms

3D : Key creator

2D : PressCad



## Tool Room Equipment



CNC Wire EDM Area



AgieCharmilles - Wire EDM



Surface Grinders



Horizontal CNC Machining Center



Vertical CNC Machining Center



## Tool Room Overview





## Stamping Presses from 25 Tons to 800 Tons (120 units)






## Secondary Processes: Robotic Welding, Staking & Tapping



## Quality System



### Certificat

Certificate

N° 2007/29622b

AFNOR Certification certifies that the management system implemented by:  
AFNOR Certification certifie que le système de management mis en place par:

**KUNSHAN LEMTECH PRECISION ENGINEERING CO., LTD.**  
昆山联德精密机械有限公司

for the following activities:  
pour les activités suivantes:

**MANUFACTURING OF PRECISION STAMPED PARTS.**  
精密冲压件的生产

has been assessed and found to meet the requirements of:  
a été évalué et jugé conforme aux exigences requises par:

**ISO 9001 : 2008**

and is deployed on the following locations:  
et est déployé sur les sites suivants:

Minyou Road, Mould Zone, Hi-Tech Industrial Park, Kunshan Development Zone,  
JIANGSU P.R.China  
中国江苏省昆山开发区高科技工业园模具社区民友路  
Extended facility: N°828 Wei Shan Hu Road, Kunshan Development Zone  
JIANGSU P.R.China  
中国江苏省昆山开发区巍山南路828号

This certificate is valid from (year/month/day) 2010-07-16 until 2013-07-15  
Ce certificat est valable à compter du (année/mois/jour) 2010-07-16 jusqu'au 2013-07-15


Managing Director of AFNOR Certification  
Directrice Générale d'AFNOR Certification

*F. MÉAUX*

F. MÉAUX

afnor CERTIFICATION

11 rue Francis de Pressensac - 33571 La Plaine Saint-Denis Cedex - France - T. +33 (0)1 41 42 90 00 - F. +33 (0)1 49 17 96 00  
SAS au capital de 16 967 000 € - 479 676 863 RCS Nanterre - [www.afnor.org](http://www.afnor.org)



### Certificat

Certificate

N° 2007/29623b  
N° IATF : 0106426

AFNOR Certification certifies that the management system implemented by:  
AFNOR Certification certifie que le système de management mis en place par:

**KUNSHAN LEMTECH PRECISION ENGINEERING CO., LTD.**  
昆山联德精密机械有限公司

for the following activities:  
pour les activités suivantes:

**MANUFACTURING OF PRECISION STAMPED PARTS FOR AUTOMOBILES.**  
汽车用精密冲压件的生产

has been assessed and found to meet the requirements of:  
a été évalué et jugé conforme aux exigences requises par:

**ISO/TS 16949 : 2009**

With the exclusion of chapter 7.3 of the technical specification (The exclusion of manufacturing process design is not permitted).  
Avec l'exclusion du chapitre 7.3 de la spécification technique (L'exclusion de la conception des processus de fabrication n'est pas autorisée)

and is deployed on the following locations:  
et est déployé sur les sites suivants:

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CERTIFICATION 

STE10038

**CERTIFICATE OF REGISTRATION**

**Kunshan Lemtech Precision Engineering Co., Ltd.**

Manufacturing of Precision Stamped Parts.

No. 28, Minyou Road, Mould Zone, Hi-tech Industrial Park, Kunshan City, Jiangsu Province, PRC

AFNOR (AFNOR) certifies that all the arrangements covering the above mentioned activities and facilities are established to meet the requirements of the international standards:

**ISO 14001 : 2004**

have been examined and found conform.

ORIGINAL DATE OF CERTIFICATION 14-MAY-2010	DATE OF ISSUE 14-MAY-2010	DATE OF EXPIRY 13-MAY-2013
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APPROVED BY *Weslee*

ENVIRONMENTAL MANAGEMENT  
ISO 14001

ACCREDITED BY  
IATF 16949  
GROUP MEMBER

ESMÉLINA NEDELIC  
Deputy Manager  
ON BEHALF OF  
KUNSHAN LEMTECH (KUNSHAN) LTD.

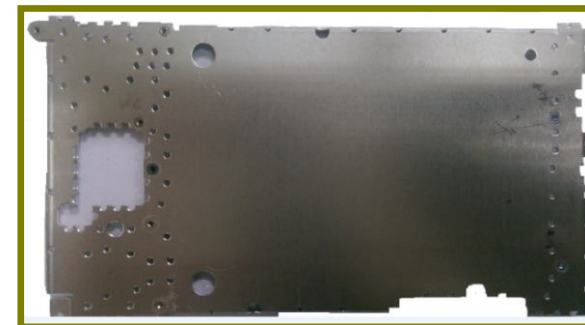
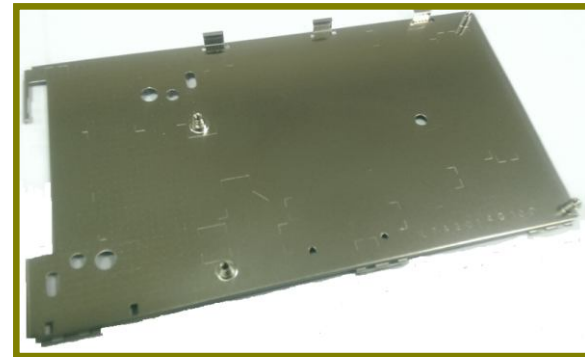
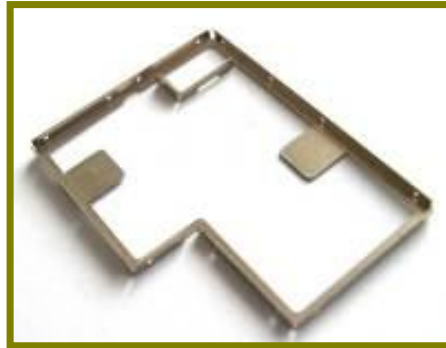
afnor CERTIFICATION

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# Stamping Solution in Mobile

## Stamping for Consumer Electronics



**Power/Volume/Ear Key of Mobile Phone series**



**Cellphone Earphone Ring**



**Cellphone Volume Key**



**Cellphone Power Key**



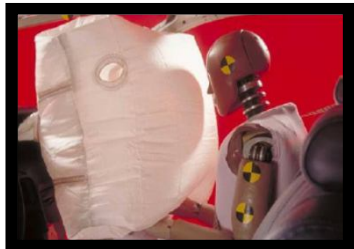
**Cellphone Volume Key**

# Automotive Business



## Parts For Various Automotive Applications

### Airbag Systems



### Seatbelt Systems



### Door Hinges



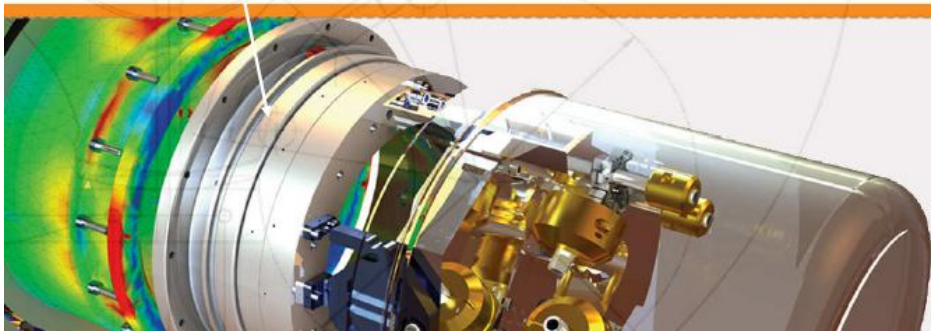
### Sunroof and Others



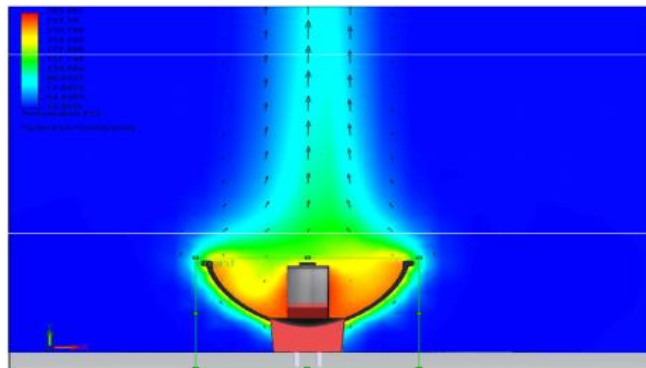
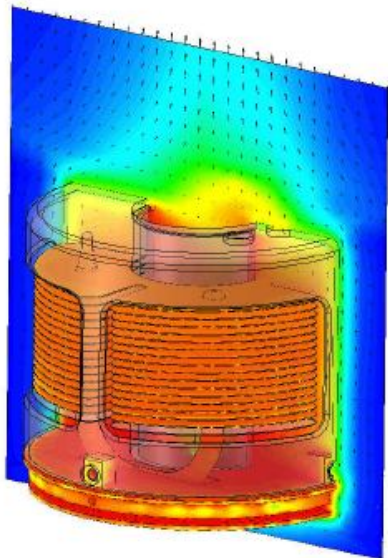
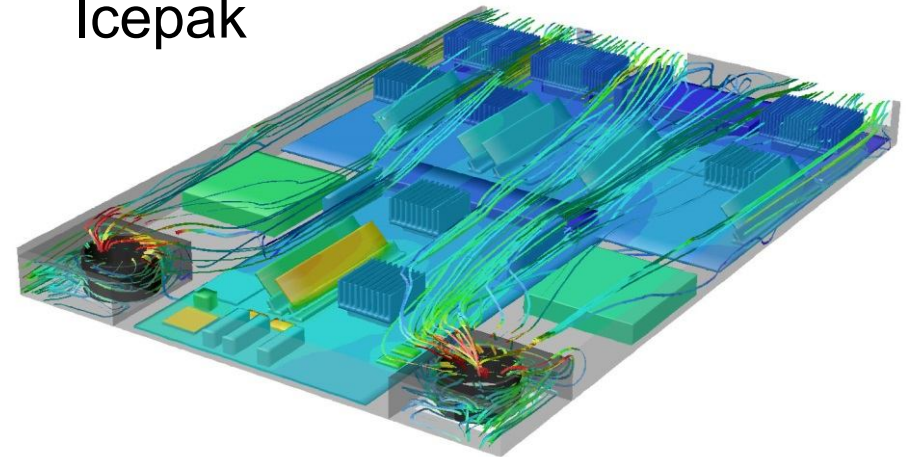
# Thermal Solution in 3C Products

## R & D Design Software - Simulation

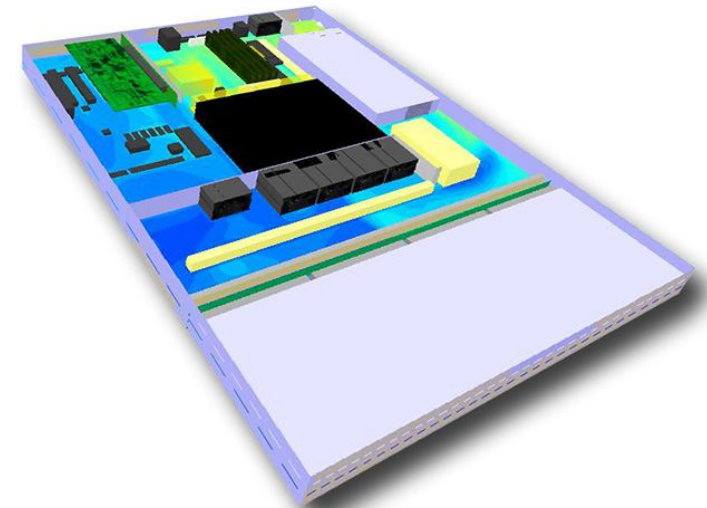
SolidWorks Flow Simulation



Icepak

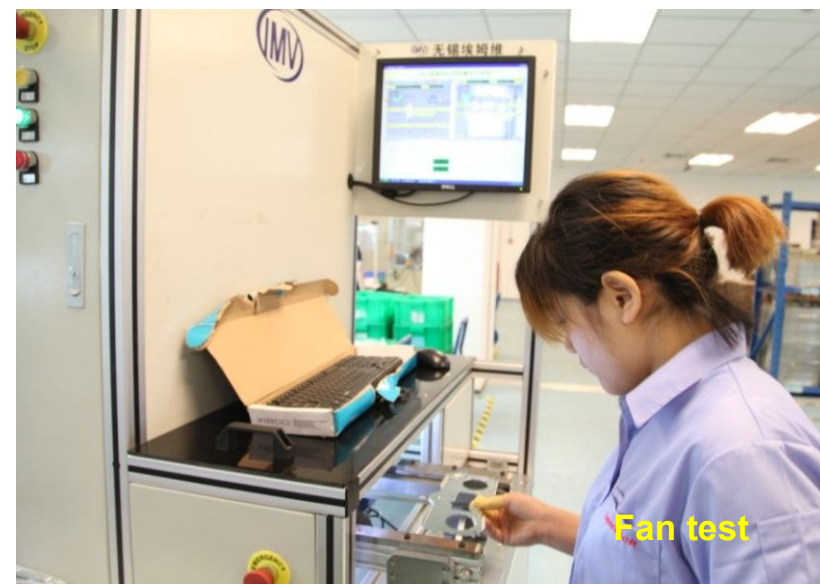


Flotherm



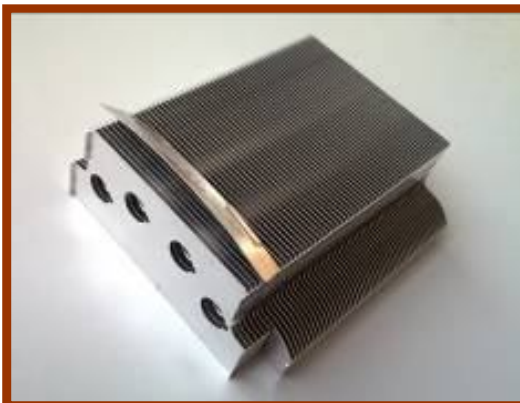
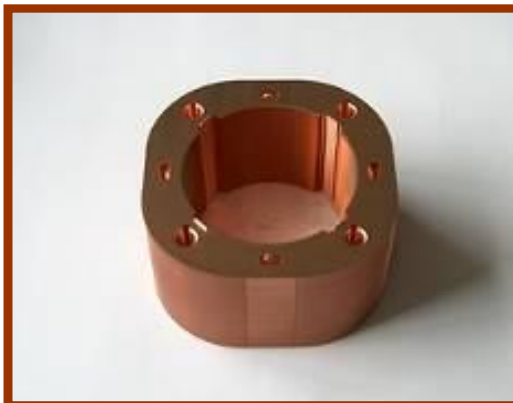


## Thermal Module Assembly & Test Equipment

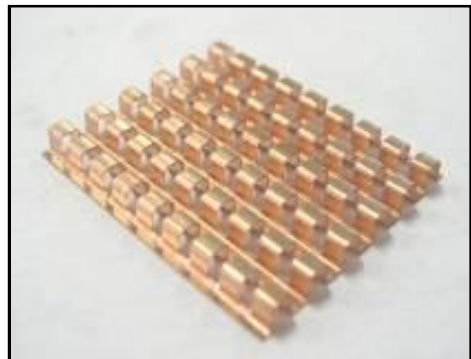
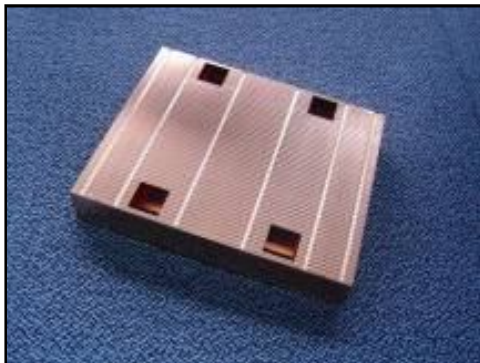
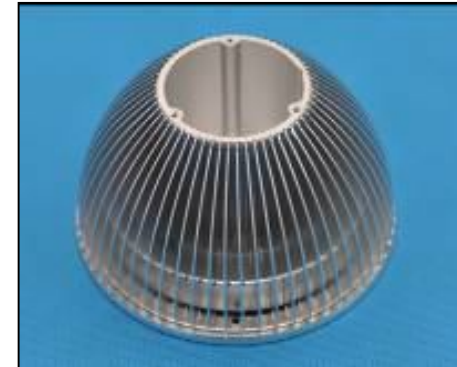




## Our Products – Heat Sinks for Consumer Electronics

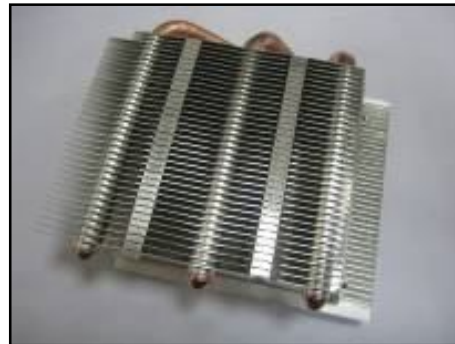
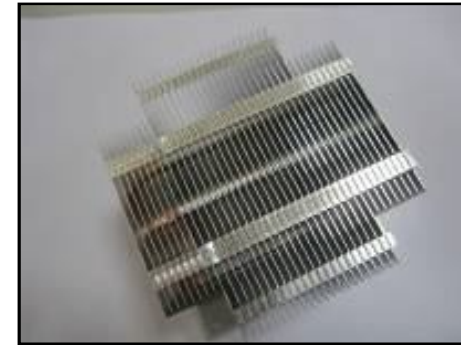
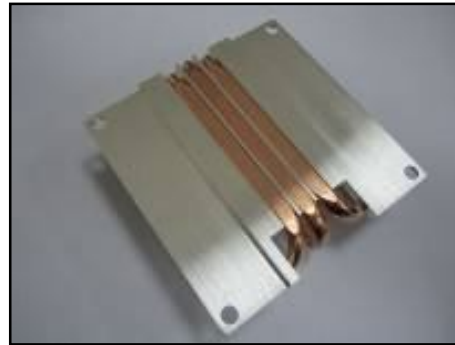


## Heat Sinks and Stampings for Consumer Electronics





## SOLDER-FREE Heat Sink Solution for Enterprise Computing





New Technology developing for Server

The cooling system plays a crucial role in a data center system. It dominates the concept of construction, facility/operation cost and efficiency.

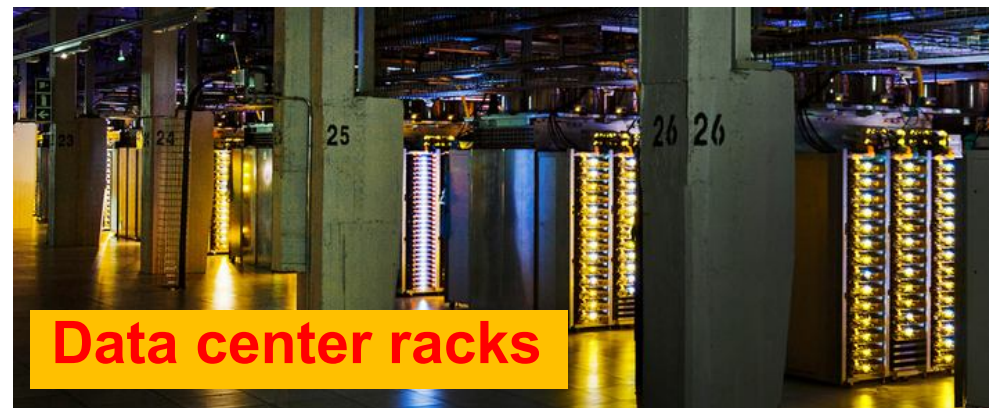
**Cooling tower**



**Chiller**



**Hot Aisle**

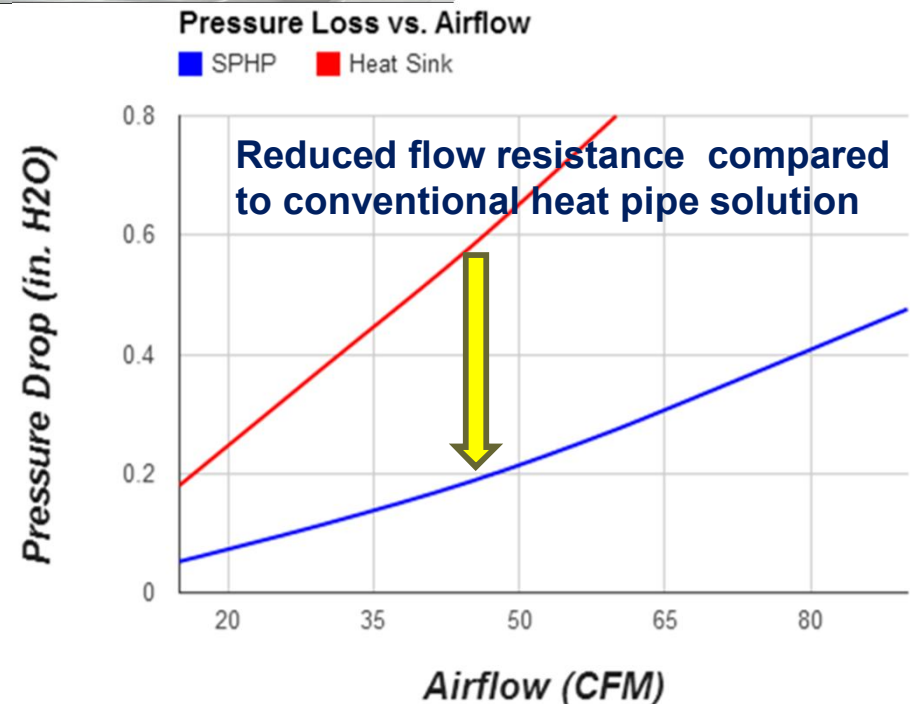
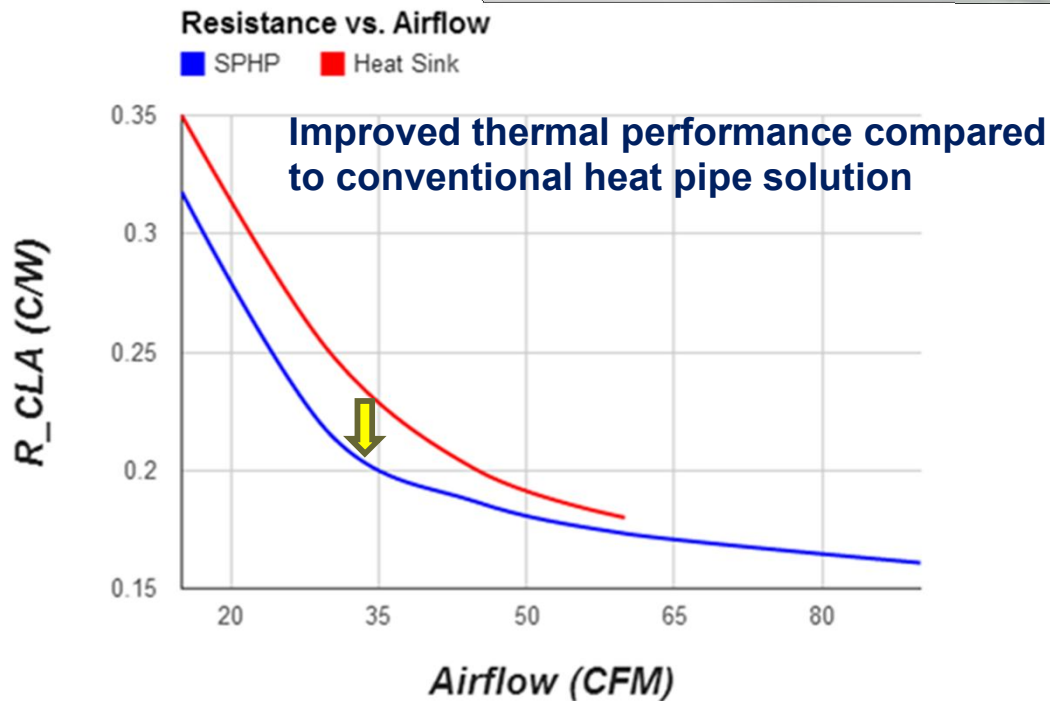


**Data center racks**

•Source: <http://www.google.com/about/datacenters/>

- Cost of data center scales nearly proportional to the server's **airflow/KW**
- Cooling systems utilize as much as 40% of total **facility power**

- **Innovative design to increase performance and reduce cost**
  - Passive, two-phase device with remote condenser
  - Minimize gravity impact at performance
  - Allows for compliance on evaporators(alleviates co-planarity issues)
  - Flexible placement of evaporators and condenser
  - Higher thermal performance that can enable use of high power CPUs
  - Low profile implementation to reduce server flow resistance significantly
  - More fin area(bigger condenser) for better heat transfer





- **MarketsandMarkets research** : Global data center cooling market will come in **10.4%** annual growth over the next four years.
- **Intel's financial statements for Data Center Group** : 2013 revenues were \$11.2 billion and about 19 million CPUs (and heat sinks) sold.
- **DCD Intelligence** : data center market will grow at **15%** per year
- Data Center hardware spend is expected to surpass \$106 billion in 2014 and \$126 billion in 2015 and about **\$10 billion** of this spend is on thermal/mechanical systems

### Potential customers include:

HP, Amazon, IBM, Google, Dell, Facebook, Oracle, Cisco, Twitter, Rackspace, Lenovo, NEC, Huawei, Fujitsu, Hitachi

## Lemtech superiority

*Skilled manufacture – AL  
Braze Technology*

*Advanced Design &  
Technology*

*Excellent customer service  
and relationship*

**Leverage the next generation technology to affect  
any potential markets and bring up profit !**

# Slide Rails developing for Server

## Slide Rails for Enterprise Enclosures *(inc Tool-Less Design Options)*

Wide View





## Front Mounting

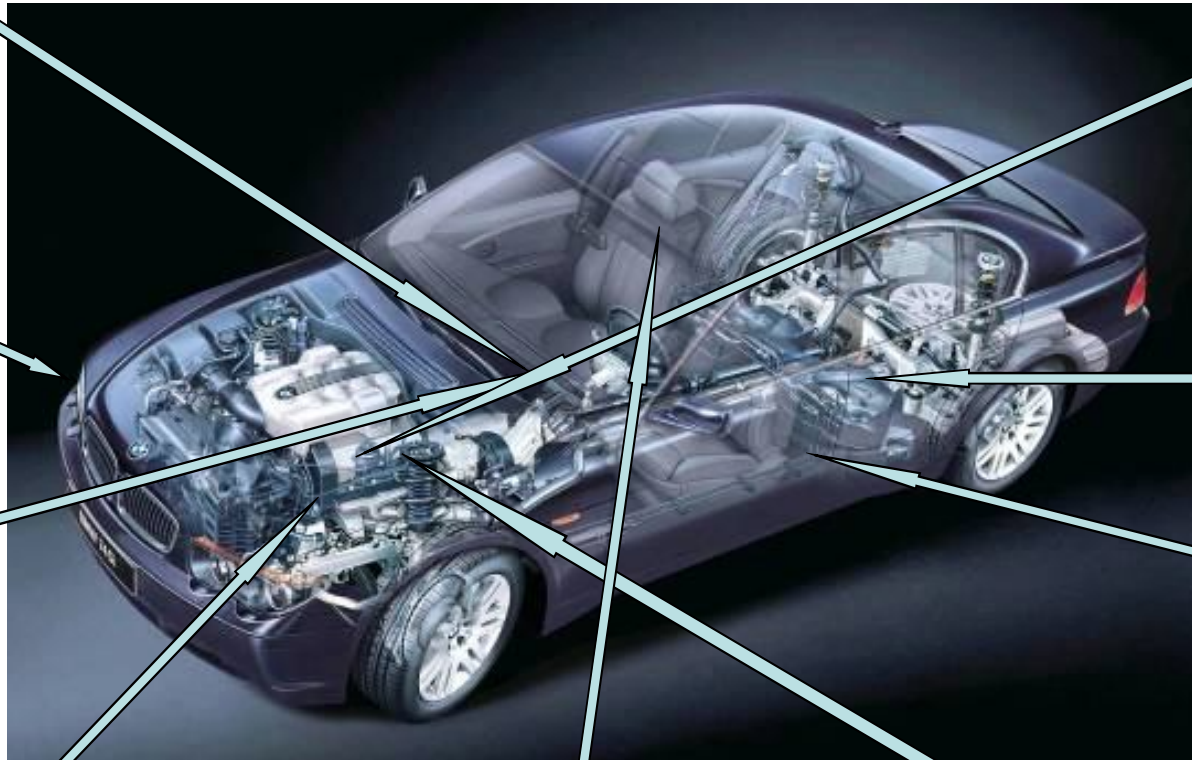


## Rear Mounting



# Our Valued Customers

## Automotive





## Computing & Consumer Electronics



AAVID  
THERMALLOY



UBIQUITI  
NETWORKS

ASUS®



DELL™

FLEXTRONICS®

FURUKAWA ELECTRIC

FOXCONN®  
Advancing Through Innovation



JABIL

JUNIPER®  
NETWORKS

**Nidec**  
All for dreams



**TOSHIBA**  
Leading Innovation >>>

# Financial Report

單位：新台幣仟元

	2013Q1	2013Q2	2013Q3	2013Q4	2014Q1	2014Q2	2014Q3
合併營收	420,642	459,201	639,526	595,522	616,858	689,635	877,866
銷貨毛利	90,606	99,207	145,507	136,132	121,620	155,980	205,361
營業淨利	33,118	32,734	69,056	36,763	31,299	73,932	111,108
稅後淨利	26,340	22,260	59,376	23,257	28,535	53,172	45,544
EPS	0.80	0.68	1.8	0.71	0.87	1.62	1.39



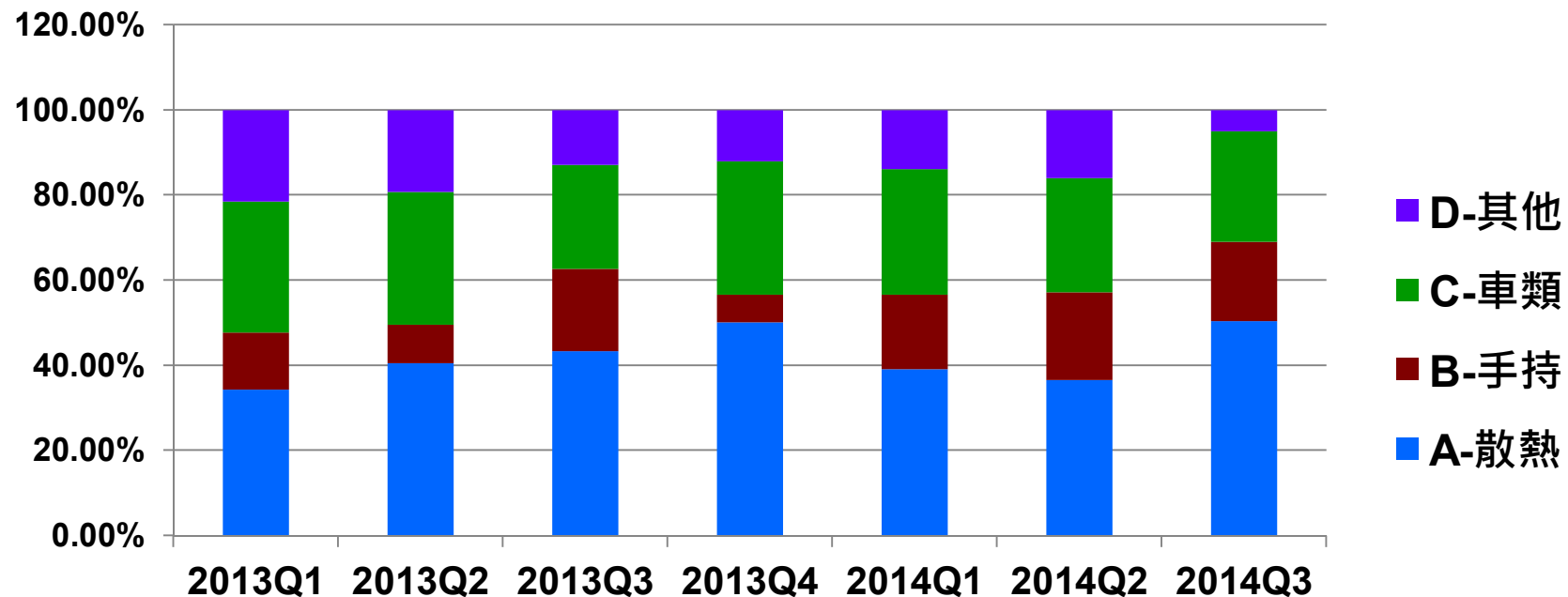
## 近六季財務比率表

		2013Q1	2013Q2	2013Q3	2013Q4	2014Q1	2014Q2	2014Q3
獲力能力	毛利率(%)	21.54	21.6	22.75	22.86	19.72	22.62	23.39
	費用率(%)	13.67	14.48	11.95	16.69	14.64	11.90	10.74
	營業利益率(%)	7.87	7.13	10.8	6.17	5.07	10.72	12.66
財務結構	負債比率(%)	32.71	46.14	47.16	52.68	48.66	57.16	59.53
	現金與約當現金 (仟元)	120,260	188,198	193,396	378,673	244,879	286,488	440,413
償債能力	流動比率(%)	212.03	145.71	142.43	132.75	139.31	164.75	156.56
	速動比率(%)	171.37	120.15	118.32	111.53	110.49	138.1	135.07
經營績效	應收款項週轉天數	116	112	108	115	95	99	95
	存貨週轉天數	48	44	41	44	45	42	38
	應付款項週轉天數	108	97	99	129	110	108	109

# 近六季簡明資產負債表

	2013Q1	2013Q2	2013Q3	2013Q4	2014Q1	2014Q2	2014Q3
流動資產	1,064,783	1,134,586	1,219,381	1,475,767	1,345,217	1,589,113	1,950,860
不動產、廠房 及設備	408,671	449,803	483,252	569,940	618,253	601,074	602,758
其他資產	105,402	147,316	156,493	111,849	74,437	104,225	115,717
資產總額	1,578,856	1,731,705	1,859,126	2,157,556	2,037,907	2,294,412	2,669,335
流動負債	502,192	778,679	856,138	1,111,704	965,663	964,548	1,246,052
非流動負債	14,216	20,248	20,574	24,867	26,028	346,860	343,018
負債總額	516,408	798,927	876,712	1,136,571	991,691	1,311,408	1,589,070
權益總額	1,062,448	932,778	982,414	1,020,985	1,046,216	983,004	1,080,265

	2013Q1	2013Q2	2013Q3	2013Q4	2014Q1	2014Q2	2014Q3
A-散熱	34.27%	40.57%	43.31%	50.14%	39.11%	36.52%	50.39%
B-手持	13.47%	9.02%	19.38%	6.44%	17.51%	20.72%	18.64%
C-車類	30.71%	31.19%	24.43%	31.34%	29.57%	26.73%	26.06%
D-其他	21.55%	19.22%	12.88%	12.08%	13.81%	16.04%	4.92%





## LEMTECH

*...Leading Engineering & Manufacturing Technology*

***Your Trusted Partner in Business***

[www.ky-lemtech.com](http://www.ky-lemtech.com)

